

EV Group brings high-speed, high-precision metrology to 3D heterogeneous integration – November 15, 2021

www.semiconductordigest.com

November 15, 2021



Top Stories

SEMICON Europa 2021 opens tomorrow with executive forum, smart technologies and digital transformation in spotlight

SEMICON Europa 2021, Europe's premier gathering of the entire electronics design and manufacturing supply chain, opens tomorrow for the latest insights from visionaries and industry leaders on smart technologies, digital transformation, and how the microelectronics industry can enable a secure and sustainable digital future. **More>>**



The NexION® 5000 multi-quadrupole ICP-MS — the first in its category to boast four quads — is innovatively designed to meet and exceed the demanding requirements of ultra-trace elemental applications. This multi-award-winning instrument is equipped with a host of new and proprietary technologies which together surpass traditional triple-quad capabilities and redefine your expectations. LEARN MORE.

Tech News

EV Group brings high-speed, high-precision metrology to 3D heterogeneous integration

EV Group today unveiled the EVG 40 NT2 automated metrology system, which provides overlay and critical dimension (CD) measurements for wafer-to-wafer (W2W), die-to-wafer (D2W) and die-to-die (D2D) bonding as well as maskless lithography applications. **More>>**

Powerful new semiconductor tool introduced by Park Systems combines atomic force microscopy with white light interferometry

Park Systems, a manufacturer of Atomic Force Microscopes, presents Park NX-Hybrid WLI, the first fully integrated system that combines Atomic Force Microscopy (AFM) with White Light Interferometer (WLI) profilometry. More>>

Smart textiles: High performance, breathable fabric to power small electronics

Scientists have created a new triboelectric fabric that generates electricity from the movement of the body while remaining flexible and breathable. <u>More>></u>



SEMICON West 2021 Hybrid Event | Dec 7-9

Join SEMICON West In-Person or On-Demand and hear outstanding keynotes from AMD, Blue Shield of California, EMD Electronics, Harvard, KLA, Lam Research, RapidRating, shift7, Stanford, Tokyo Electron, and more. Get answers about today's megatrends driving business and change from AI and Big Data to Smart Manufacturing and Smart MedTech. **Register today.**

Business News

Classiq to collaborate with the Fraunhofer Institute

Classiq, which provides a breakthrough Quantum Algorithm Design platform, announced today that

Featured Product



Pfeiffer Vacuum ATH 2804 M/MT and ATH 3204

M/MT magnetically levitated turbopumps are designed for harsh semiconductor applications. They offer a gas throughput of over 5,000 sccm of nitrogen for non-heated applications and up to 1,500 sccm of argon at 65°C in corrosive applications. **Learn more.**



Webcasts and Technology Papers

Temperature Solutions for Semiconductor Production

<u>View Paper</u>

Particles, Processes, and Planning: Synergies to Improve CMP Yield View Paper

Managing the Emission Properties of MicroLEDs Through Photonic Bandgap Engineering

View Paper

Field Digital Demand Generation Fault Hunter AN AMO WW Q421

<u>View Paper</u>

Consistent Atomic Layer Deposition Processes Demand Consistent
ALD Valve Actuation
View On Demand

Analysis of Metallic Impurities in Organic Solvents Used in IC Fabrication With the NexION 5000 ICP-MS

View Paper

Backside Protection of Wafer-Level Chip Scale Packages Improves Handling and Reliability

View Paper

Ultra-Trace Quantification of Non-Metals in Sulfuric Acid Solutions Using the NexION 5000 ICP-MS Under Different Cell Gas Conditions

View Paper

In-line Airborne Particle Sensing Supports Faster Response to Contamination Excursions

View Paper

Analysis of Metallic Impurities in Si Wafers Using Fully Automated VPD-ICP-MS

View Paper

Fluxless Soldering in Activated Hydrogen Atmosphere
View Paper



Web Editor

Shannon Davis 603-547-5309

sdavis@semiconductordigest.com

Subscription Information

Subscribe to our other newsletters

Forward to a colleague or a friend.

To contact us, click here